

**IN THE ABSTRACT**

~~The invention relates to a~~ method and device are  
provided~~used~~ to reshape a set of conducting elements which are  
distributed over the inner face of an electronic module, said set  
of conducting elements forming means of positioning the module on  
a motherboard and/or electromagnetic armour means for the inner  
face of the module and/or means providing an electrical  
interconnection with the motherboard. ~~According to the~~  
~~invention, the~~ The method comprises a reflow step whereby the  
module is subjected to the stress reflow method in a volume  
comprising walls having pre-determined shapes in order to enable  
destressing between at least some of the constituent elements of  
the module, such that the tips of the free ends of the set of  
conducting elements conform to the shape of a pre-determined two-  
dimensional or three-dimensional case. In one particular  
embodiment, the volume comprising the walls having pre-determined  
shapes is a volume in which a first wall, which is intended to be  
in contact with the tips of the free ends of the set of  
conducting elements, is a plane wall. In this case, the pre-  
determined two-dimensional or three-dimensional case is a plane  
and the reshaping consists in restoring the flatness thereof.